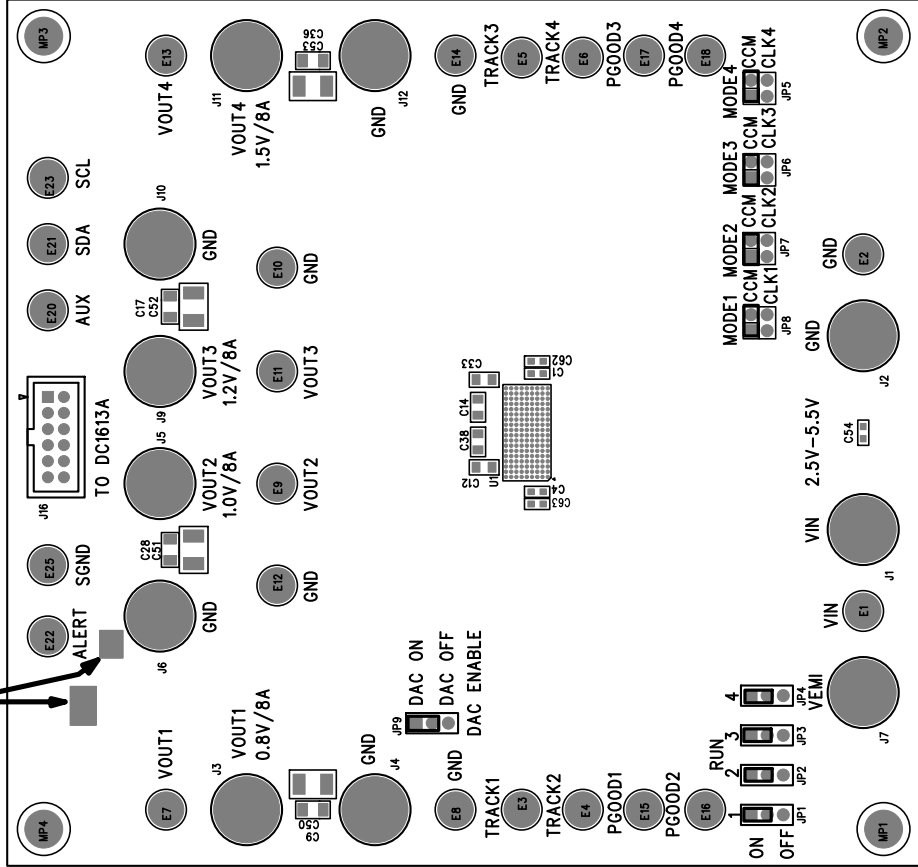


REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
-	4	PRODUCTION	Le W.
			DATE
			06-21-22

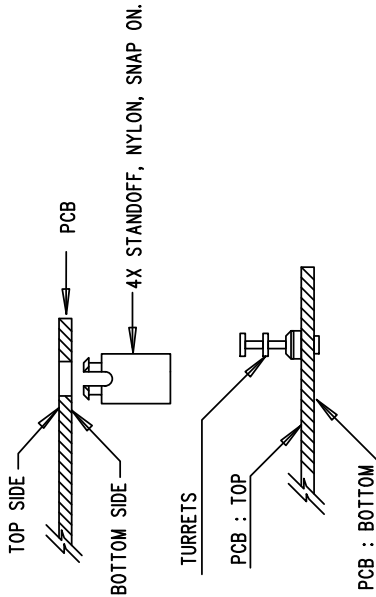
8. MARK "-1" FOR LTM4710-1  
MARK "B" FOR 3164A-B



L1-COMPONENT SIDE

### NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610. MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



8. SEE THE BILL OF MATERIALS TO MARK "-1" AND "B" FOR LTM4710 AND 3164A- WITH BLACK PERMANENT MARKER.



TITLE: ASSEMBLY TOP DRAWING

LOW 2.5V-5.5Vin, QUAD 8A STEP DOWN  $\mu$ MODULE REGULATOR

SIZE	IC NO.	LTM4710/LTM4710-1	REV
N/A	DEMO CIRCUIT	DC3164A-A/B	4
FILENAME: DC3164A4.PCB			SHT 1 OF 2